

Features

- Trench LV MOSFET Technology
- ESD Protected Up To 2KV (HBM)
- Fast Switching Speed
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

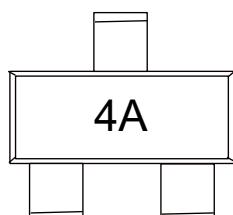
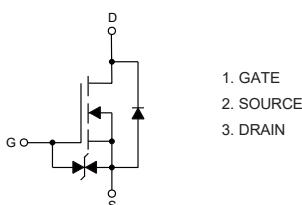
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 500°C/W Junction to Ambient^(Note 2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous $T_A=25^\circ\text{C}$	I_D	0.75	A
$T_A=70^\circ\text{C}$	I_D	0.6	
Drain Current-Pulsed ^(Note 3)	I_{DM}	3	A
Power Dissipation ^(Note 4)	P_D	0.25	W

Note:

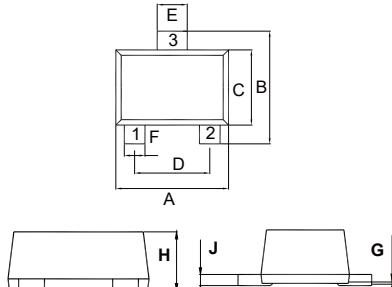
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of R_{GJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code



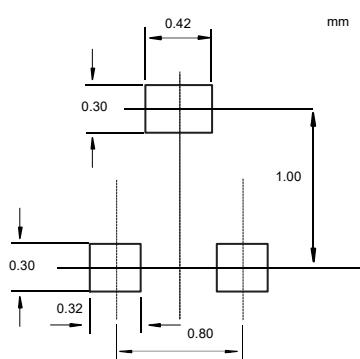
N-Channel MOSFET

SOT-723



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.043	0.051	1.10	1.30	
B	0.043	0.051	1.10	1.30	
C	0.028	0.035	0.70	0.90	
D	0.031		0.80		TYP.
E	0.009	0.017	0.22	0.42	
F	0.005	0.013	0.12	0.32	
G	0.000	0.002	0.00	0.05	
H	0.017	0.021	0.43	0.54	
J	0.003	0.006	0.08	0.15	

Suggested Solder Pad Layout



ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	20			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±10V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	μA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.35	0.7	1.1	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =4.5V, I _D =500mA		190	300	mΩ
		V _{GS} =2.5V, I _D =400mA		280	400	mΩ
		V _{GS} =1.8V, I _D =200mA		480	700	mΩ
Forward transconductance	g _{FS}	V _{DS} =10V, I _D =500mA		1.6		s
Gate Resistance	R _g	f=1 MHz, Open drain		37		Ω
Diode Characteristics						
Continuous Body Diode Current	I _S				0.75	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =500mA			1.2	V
Reverse Recovery Time	t _{rr}	I _F =0.5A, dI _F /dt=100A/μs		12.5		ns
Reverse Recovery Charge	Q _{rr}			0.7		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =16V,V _{GS} =0V,f=1MHz		27		pF
Output Capacitance	C _{oss}			9.5		
Reverse Transfer Capacitance	C _{rss}			4.6		
Total Gate Charge	Q _g	V _{GS} =4.5V,V _{DS} =10V,I _D =1A		0.78		nC
Gate-Source Charge	Q _{gs}			0.27		
Gate-Drain Charge	Q _{gd}			0.18		
Turn-On Delay Time	t _{d(on)}	V _{GS} =4.5V,V _{DS} =10V, I _{DS} =0.5A,R _G =10Ω		3		ns
Turn-On Rise Time	t _r			19		
Turn-Off Delay Time	t _{d(off)}			10.8		
Turn-Off Fall Time	t _f			24		

Curve Characteristics

Fig.1 - Typical Output Characteristics

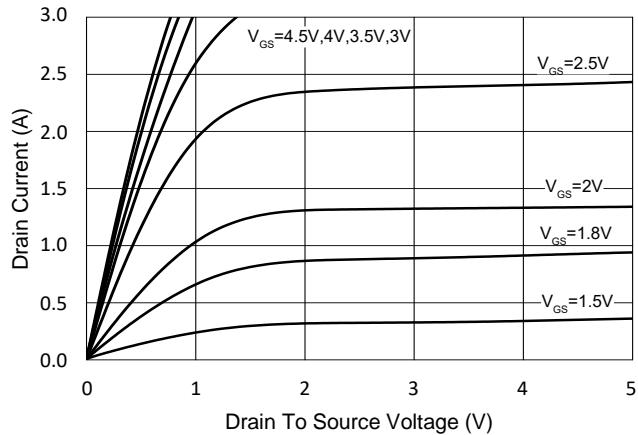


Fig.2 - Transfer Characteristic

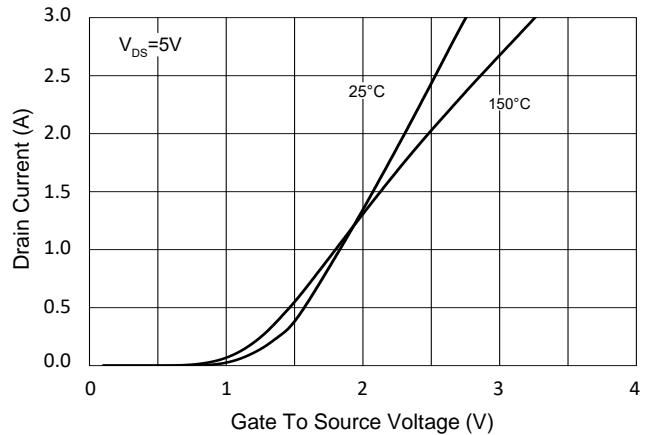


Fig.3 - $R_{DS(ON)}$ - V_{GS}

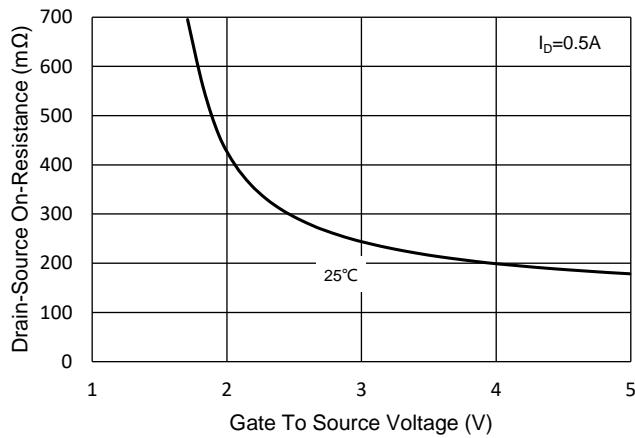


Fig.4 - $R_{DS(ON)}$ - I_D

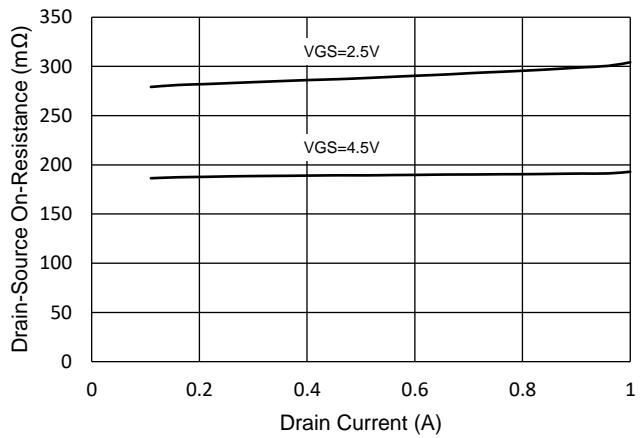


Fig.5 - Capacitance Characteristics

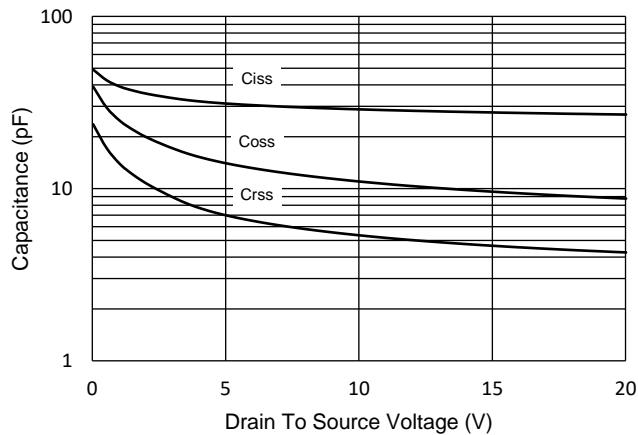
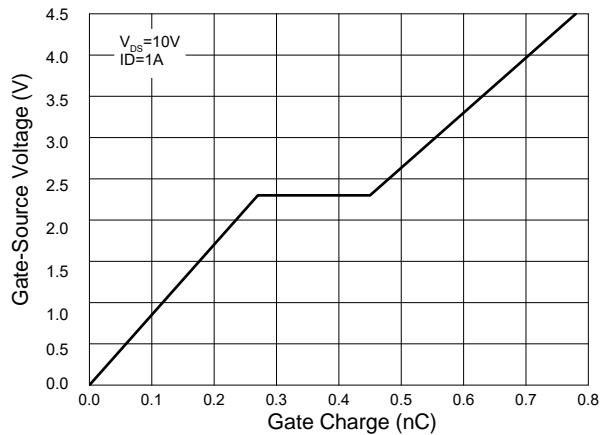


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

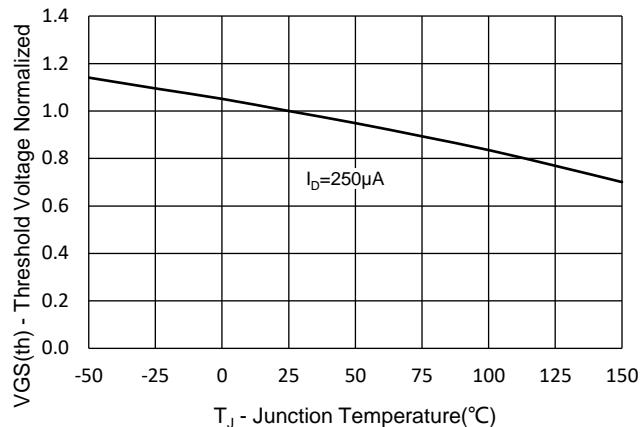


Fig.8 - Normalized On Resistance Characteristics

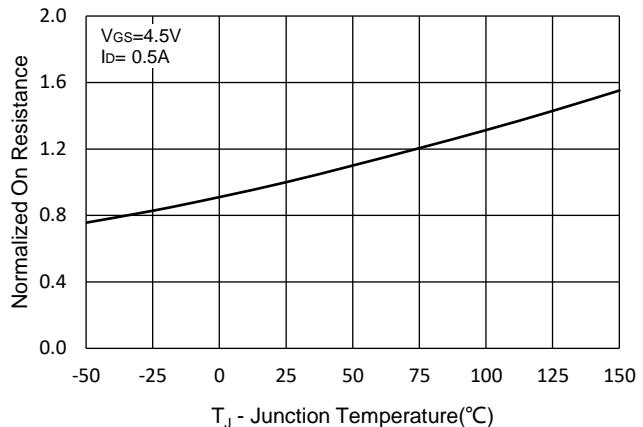


Fig.9 - I_S - V_{SD}

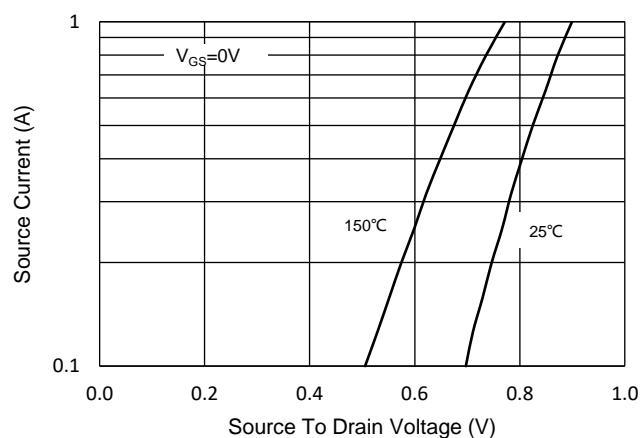


Fig.10 - Drain Current

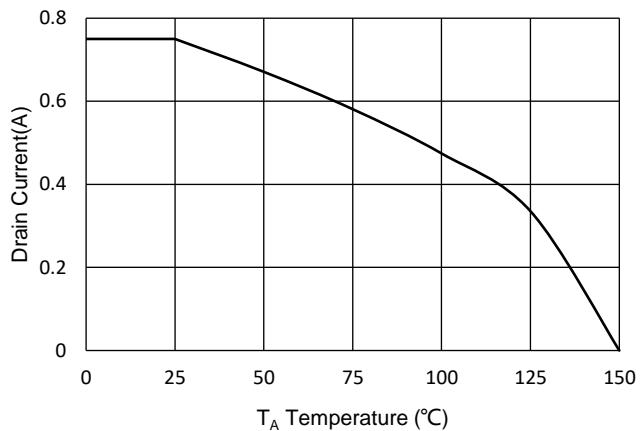
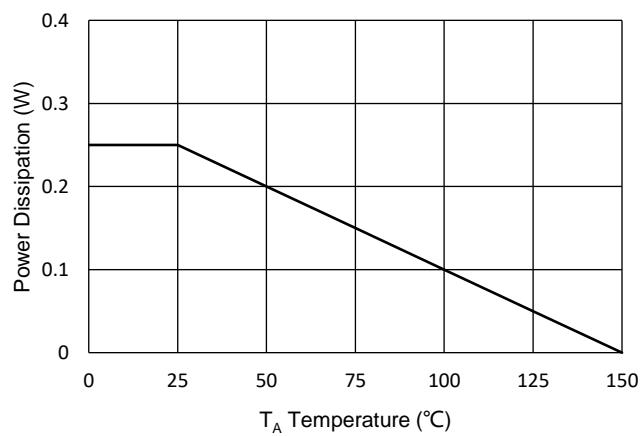


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

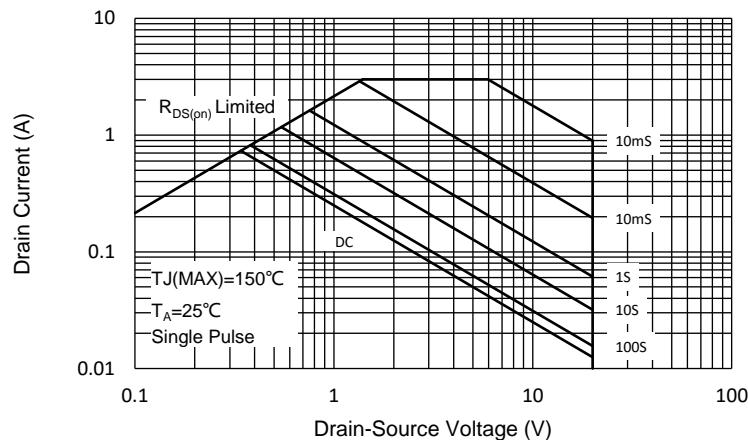
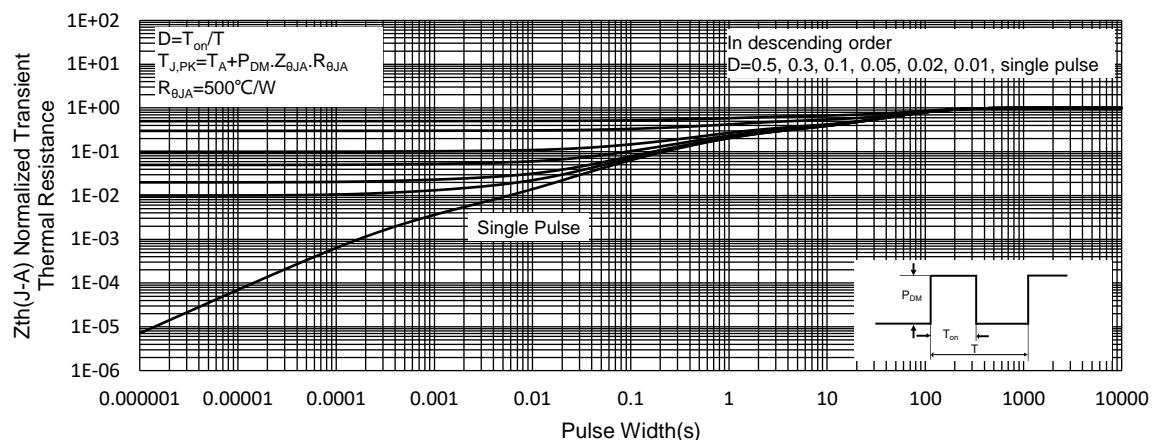


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:8Kpcs/Reel

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